

METHOD FOR MAKING A PACKAGE STRUCTURE WITH A CAVITY

Abstract

A method for making a package structure with a cavity comprises the following steps: (a) providing a chip having a circuit disposed thereon and a plurality of first bonding pads disposed around the circuit; (b) providing a multi-layer ceramic substrate having a cave formed thereon and a plurality of second bonding pads disposed around the cave, wherein the cave and the plurality of second bonding pads are respectively corresponding to the circuit and the plurality of first bonding pads; (c) applying an adhesive layer to the surface of the substrate with the cave and the second pads exposed from the adhesive layer; (d) tightly bonding the chip and the multi-layer ceramic substrate together such that the circuit of the chip is corresponding to the cave of the multi-layer ceramic substrate so as to form a cavity, and then electrically connecting the plurality of first bonding pads with the plurality of second bonding pads.